



DAC707 DAC708 DAC709

Microprocessor-Compatible 16-BIT DIGITAL-TO-ANALOG CONVERTERS

FEATURES

- TWO-CHIP CONSTRUCTION
- HIGH-SPEED 16-BIT PARALLEL, 8-BIT (BYTE) PARALLEL, AND SERIAL INPUT MODES
- DOUBLE-BUFFERED INPUT REGISTER CONFIGURATION
- V_{OUT} AND I_{OUT} MODELS

DESCRIPTION

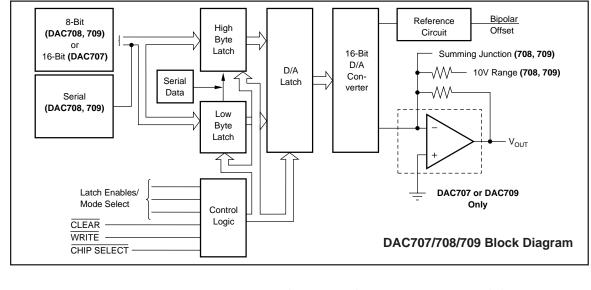
The DAC708 and DAC709 are 16-bit converters designed to interface to an 8-bit microprocessor bus. 16bit data is loaded in two successive 8-bit bytes into parallel 8-bit latches before being transferred into the D/A latch. The DAC708 and DAC709 are current and voltage output models respectively and are in 24-pin hermetic DIPs. Input coding is Binary Two's Complement (bipolar) or Unipolar Straight Binary (unipolar, when an external logic inverter is used to invert the MSB). In addition, the DAC708/709 can be loaded serially (MSB first).

The DAC707 is designed to interface to a 16-bit bus.

- HIGH ACCURACY: Linearity Error ±0.003% of FSR max
 Differential Linearity Error ±0.006% of FSR max
- MONOTONIC (TO 14 BITS) OVER SPECIFIED TEMPERATURE RANGE
- HERMETICALLY SEALED
- LOW COST PLASTIC VERSIONS AVAILABLE (DAC707JP/KP)

Data is written into a 16-bit latch and subsequently the D/A latch. The DAC707 has bipolar voltage output and input coding is Binary Two's Complement (BTC).

All models have Write and Clear control lines as well as input latch enable lines. In addition, DAC708 and DAC709 have Chip Select control lines. In the bipolar mode, the Clear input sets the D/A latch to give zero voltage or current output. They are all 14-bit accurate and are complete with reference, and for the DAC707, and DAC709, a voltage output amplifier. All models are available with an optional burn-in screening.



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SPECIFICATIONS

ELECTRICAL

At $T_A = +25^{\circ}C$, $V_{CC} = \pm 15V$, $V_{DD} = +5V$, and after a 10-minute warm-up, unless otherwise noted.

	DAC707JP				DAC707/708/709KH, DAC707KP			DAC707/70 709BH, SH		
PRODUCT	MIN	ТҮР	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
INPUT										
DIGITAL INPUT Resolution Bipolar Input Code (all models)	Bina	ry Two's Co	16		*	*		*	*	Bits
$ \begin{array}{c} \text{Dipolar input Code}(\text{cli}) (DAC708/709 \text{ only}) \\ \text{Logic Levels}^{(2)}: \text{V}_{\text{IH}} \\ & \text{V}_{\text{IL}} \\ & \text{I}_{\text{IH}} (\text{V}_{\text{I}} = +2.7\text{V}) \\ & \text{I}_{\text{IL}} (\text{V}_{\text{I}} = +0.4\text{V}) \end{array} $	+2.0 -1.0		+5.5 +0.8 1	Uniţ * *	bolar Straig	ht Binary * * *	*	*	* * *	V V μΑ μΑ
TRANSFER CHARACTERISTICS										
ACCURACY ⁽³⁾ Linearity Error Differential Linearity Error ⁽⁵⁾ at Bipolar Zero ^(5, 6) Gain Error ⁽⁷⁾ Zero Error ⁽⁷⁾ Monotonicity Over Spec Temp Range Power Supply Sensitivity: +V _{CC} , -V _{CC} V _{DD}	13	$\begin{array}{c} \pm 0.003 \\ \pm 0.0045 \\ \pm 0.07 \\ \pm 0.05 \\ \pm 0.0015 \\ \pm 0.0001 \end{array}$	$\begin{array}{c} \pm 0.006 \\ \pm 0.012 \\ \pm 0.30 \\ \pm 0.1 \\ \pm 0.006 \\ \pm 0.001 \end{array}$	14	±0.0015 ±0.003 ±0.003 * *	±0.003 ±0.006 ±0.006 ±0.15 * *	14	* ±0.0015 ±0.05 * *	* ±0.003 ±0.10 * ±0.003 *	% of FSR ⁽⁴⁾ % of FSR % of FSR % of FSR Bits % of FSR/%V _{CC} % of FSR/%V _{DD}
DRIFT (Over Spec Temp Range ⁽³⁾) Total Error Over Temp Range ⁽⁸⁾ Total Full Scale Drift Gain Drift Zero Drift: Unipolar (DAC708/709 only) Bipolar (all models) Differential Linearity Over Temp ⁽⁵⁾ Linearity Error Over Temp ⁽⁵⁾		±0.08 ±10 ±10 ±5	±30 ±15 ±0.012 ±0.012		* * <u>+</u> 2.5 *	± 0.15 ± 25 ± 25 ± 12 ± 0.009 , -0.006 ± 0.006		* ±7 ±1.5 ±4	±0.10 ±15 ±15 ±3 ±10 *	% of FSR ppm of FSR/°C ppm of FSR/°C ppm of FSR/°C % of FSR % of FSR
$\begin{array}{l} \textbf{SETTLING TIME (to \pm 0.003\% \text{ of FSR})^{(9)}}\\ \textbf{Voltage Output Models}\\ \textbf{Full Scale Step (2k\Omega load)}\\ \textbf{1LSB Step at Worst Case Code^{(10)}}\\ \textbf{Slew Rate}\\ \textbf{Current Output Models}\\ \textbf{Full Scale Step (2mA): 10 to 100\Omega Load}\\ \textbf{1k\Omega Load}\\ \end{array}$		4 2.5 10			* * * 350 1	8 4		* * *	8 4	μs μs V/μs ns μs
OUTPUT										
VOLTAGE OUTPUT MODELS Output Voltage Range DAC709: Unipolar (USB Code) Bipolar (BTC Code) DAC707 Bipolar (BTC Code) Output Current Output Current Output Impedance Short Circuit to Common Duration	±5	±10 0.15 Indefinite		*	0 to +10 ±5, ±10 *		*	* * *		V V mA Ω
CURRENT OUTPUT MODELS Output Current Range (±30% typ) DAC708: Unipolar (USB Code) Bipolar (BTC Code) Unipolar Output Impedance (±30% typ) Bipolar Output Impedance (±30% typ) Compliance Voltage					0 to -2 ±1 4.0 2.45 ±2.5			* * *		mA mA kΩ V

The information provided herein is believed to be reliable; however, BURR-BROWN assumes no responsibility for inaccuracies or omissions. BURR-BROWN assumes no responsibility for the use of this information, and all use of such information shall be entirely at the user's own risk. Prices and specifications are subject to change without notice. No patent rights or licenses to any of the circuits described herein are implied or granted to any third party. BURR-BROWN does not authorize or warrant any BURR-BROWN product for use in life support devices and/or systems.



ELECTRICAL (CONT)

At $T_A = +25^{\circ}$ C, $V_{CC} = \pm 15$ V, $V_{DD} = +5$ V, and after a 10-minute warm-up, unless otherwise noted.

		DAC707JP			DAC707/708/709KH, DAC707KP		DAC707/708/ 709BH, SH			
PRODUCT	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
POWER SUPPLY REQUIREMENTS										
Voltage (all models): +V _{CC}	+13.5	+15	+16.5	*	*	*	*	*	*	V
-V _{CC}	-13.5	-15	-16.5	*	*	*	*	*	*	V
V _{DD} Current (No Load, +15V Supplies)	+4.5	+5	+5.5	*	*	*	*	*	*	V
Current Output Models: +V _{CC}					+10	+25		*	*	mA
-V _{CC}					-13	-25		*	*	mA
V _{DD}					+5	+10		*	*	mA
Voltage Output Models: +V _{CC}		+16	+30		*	*		*	*	mA
-V _{CC}		-18	-30		*	*		*	*	mA
V _{DD}		+5	+10		*	*		*	*	mA
Power Dissipation (±15V supplies) Current Output Models					370	800		*	*	mW
Voltage Output Models		535			*	950		*	*	mW
TEMPERATURE RANGE										
Specification: BH Grades							-25		+85	°C
JP, KP, KH Grades	0		+70	*		*				°C
SH Grades							-55		+125	°C
Storage: Ceramic				-65		+150	-65		+150	°C
Plastic	-60		+100	*		*				°C

*Specification same as for models in column to the left.

NOTES: (1) MSB must be inverted externally prior to DAC708/709 input. (2) Digital inputs are TTL, LSTTL, 54/74C, 54/74HC and 54/74HTC compatible over the specified temperature range. (3) DAC708 (current-output models) are specified and tested with an external output operational amplifier connected using the internal feedback resistor in all tests. (4) FSR means Full Scale Range. For example, for \pm 10V output, FSR = 20V. (5) \pm 0.0015% of Full Scale Range is equal to 1 LSB in 16-bit resolution, \pm 0.003% of Full Scale Range is equal to 1 LSB in 16-bit resolution. \pm 0.006% of Full Scale Range is equal to 1 LSB in 16-bit resolution. (6) Error at input code 0000_H. (For unipolar connection on DAC708/709, the MSB must be inverted externally prior to D/A input.) (7) Adjustable to zero with external trim potentiometer. Adjusting the gain potentiometer rotates the transfer function around the bipolar zero point. (8) With gain and zero errors adjusted to zero at +25°C. (9) Maximum represents the 3σ limit. Not 100% tested for this parameter. (10) The bipolar worst-case code change is FFFF_H to 0000_H and 0000_H to FFFF_H. For unipolar (DAC708/709 only) it is 7FFF_H to 8000_H and 8000_H to 7FFF_H.

PACKAGE INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
DAC707JP	28-Pin Plastic DBL Wide DIP	215
DAC707KP	28-Pin Plastic DBL Wide DIP	215
DAC707BH	28LD Side Brazed Hermetic Dip	149
DAC707KH	28LD Side Brazed Hermetic DIP	149
DAC707SH	28LD Side Brazed Hermetic DIP	149
DAC708BH	24LD Side Brazed Hermetic DIP	165
DAC708KH	24LD Side Brazed Hermetic DIP	165
DAC708SH	24LD Side Brazed Hermetic DIP	165
DAC709BH	24LD Side Brazed Hermetic DIP	165
DAC709KH	24LD Side Brazed Hermetic DIP	165
DAC709SH	24LD Side Brazed Hermetic DIP	165

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

ABSOLUTE MAXIMUM RATINGS

$ \begin{array}{llllllllllllllllllllllllllllllllllll$
Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DAC707/708/709

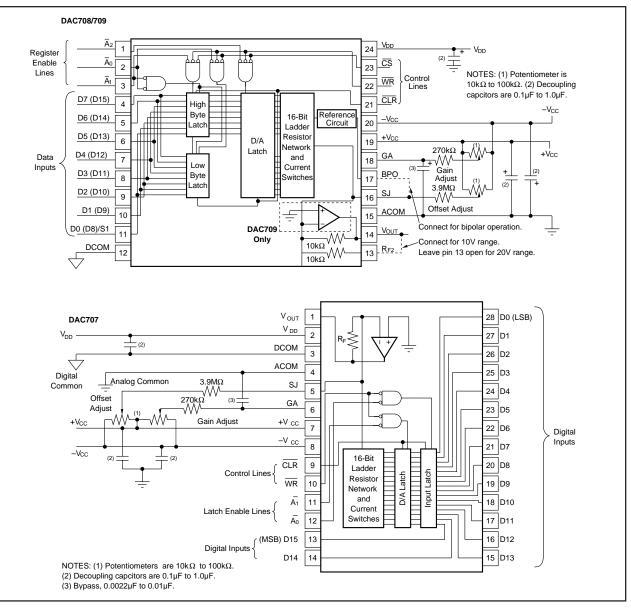


ORDERING INFORMATION

PRODUCT	TEMPERATURE	INPUT	OUTPUT
	RANGE	CONFIGURATION	CONFIGURATION
DAC707JP DAC707JP-BI ⁽¹⁾ DAC707KP DAC707KP-BI ⁽¹⁾ DAC707KH DAC707KH-BI ⁽¹⁾ DAC707BH DAC707BH DAC707BH-BI ⁽¹⁾ DAC707SH	0°C to +70°C 0°C to +70°C 0°C to +70°C 0°C to +70°C 0°C to +70°C 0°C to +70°C -25°C to +85°C -25°C to +85°C -55°C to +125°C	16-bit port 16-bit port 16-bit port 16-bit port 16-bit port 16-bit port 16-bit port 16-bit port 16-bit port 16-bit port	±10V output ±10V output
DAC707SH-BI ⁽¹⁾	-55°C to +125°C	16-bit port	±10V output
DAC708KH	0°C to +70°C	8-bit port	±1mA output
DAC708BH	−25°C to +85°C	8-bit port	±1mA output
DAC708SH	−55°C to +125°C	8-bit port	±1mA output
DAC709KH	0°C to +70°C	8-bit port	±10V output
DAC709BH	−25°C to +85°C	8-bit port	±10V output
DAC709SH	−55°C to +125°C	8-bit port	±10V output

NOTE: (1) 25 piece minimum order.

CONNECTION DIAGRAMS





DESCRIPTION OF PIN FUNCTIONS

NonLogic supply (+5V)2 A_0 E_0 DCOMDigital common3 A_1 E_0 ACOMAnalog common4D7 (D15)InSJSumming junction of the internal output op amp for the bagram.5D6 (D14)InGAGain adjust pinction of the output amplifier. Refer to Block Diagram.5D6 (D14)DGAGain adjust pinction of the output amplifier. Refer to Block Diagram.7D4 (D12)D-V_{CC}Positive supply voltage (+15V)7D4 (D12)D-V_{CC}Negative supply voltage (-15V)8D3 (D11)DCLRClear line. Sets the input latch to zero and sets the D/A latch to the input code that gives bipolar zero on the D/A output (Active low)10D1 (D9)DWRWrite control line (Active low)11D0 (D8)/SIDD15 (MSB)Data bit 15 (Most Significant Bit)13R _{F2} F_0 D13Data bit 12Data bit 12InfNGC/CO80)ND14Data bit 1315ACOMAD15Data bit 1414Your NGC/CO80)SIDD16Data bit 15DEQV/CCPD17Data bit 16CZV/RNND18Data bit 622V/RNND19Data bit 623GAGAGAGAD10Data bit 623DGCIRCIRCIRD11 <th>DAC708/709</th>	DAC708/709
VDD DD LOGIC SUPPLY (+5V)LOGIC SUPPLY (+5V) <thlogic (+5v)<="" supply="" th=""><thlogic (+5v)<<="" supply="" th=""><th>DESCRIPTION</th></thlogic></thlogic>	DESCRIPTION
VDD DDLogic supply (+5V)2Ao aLogic supply (+5V)DCOMDigital common3A,Logic supply (-5V)ACOMAnalog common4D7 (D15)In to the summing junction of the internal output op amp for the DDAC707. Offset adjust circuit is connected to the summing junction of the output amplifier. Refer to Block Diagram.5D6 (D14)In erGAGain adjust pin. Refer to Connection Diagram for gain adjust circuit.6D5 (D13)D-VocPositive supply voltage (+15V)7D4 (D12)D-VocNegative supply voltage (+15V)7D4 (D12)D-VocNegative supply voltage (-15V)7D4 (D12)DCIRClear line. Sets the input latch to zero and sets the D/A latch to the input code that gives bipolar zero on the D/A output (Active low)10D (D9)DMRWrite control line (Active low)11D (D08)/SIDDA1Enable for Input latch (Active low)11D (D08)/SIDD13Data bit 1315ACOMAD14Data bit 1315ACOMAD15Data bit 1018GAGD9Data bit 1019VocPD1Data bit 316SJ (DAC709)DD1Data bit 320-VocPD13Data bit 1018GAGD9Data bit 320-VocPD1Data bit 620-Voc	Latch enable for D/A latch (Active low)
ACOMAnalog common4D7 (D15)In dat dat datSJSumming junction of the internal output op amp for the DAC707. Offset adjust circuit is connected to the summing junction of the output amplifier. Refer to Block Diagram.5D6 (D14)In datGAGain adjust pin. Refer to Connection Diagram for gain adjust circuit.6D5 (D13)D1+V_{CC}Positive supply voltage (+15V)7D4 (D12)D1-V_{CC}Negative supply voltage (-15V)8B3 (D11)D2CIRClear line. Sets the input latch to zero and sets the D/A tatch to the input code that gives bipolar zero on the D/A output (Active low)10D1 (D9)D2WRWrite control line (Active low)10D1 (D9)D2D3Af_0Enable for input latch (Active low)11D0 (D8)/SID6D15 (MSB)Data bit 15 (Most Significant Bit)13RF2F6D14Data bit 1315ACOMArD12Data bit 1111BPOBiD13Data bit 1111BPOBiD14Data bit 1018GAGAD15Data bit 1018GAG2VCCD16Data bit 320VZCCPCD17Data bit 622WRWD18Data bit 623CSCID19Data bit 623CSCID10Data bit 623CSCID14Data bit 623	Latch enable for "low byte" input (Active low). When both A_0 and A_1 are logic "0", the serial input mode is selected and the serial input is enabled.
SJSumming junction of the internal output op amp for the DAC707. Offset adjust circuit is connected to the summing junction of the output amplifier. Refer to Block Diagram.5D6 (D14)In erGAGain adjust pin. Refer to Connection Diagram for gain adjust circuit.6D5 (D13)D-V_{CC}Positive supply voltage (+15V)7D4 (D12)D-V_{CC}Negative supply voltage (-15V)8D3 (D11)DCLRClear line. Sets the input tatch to zero and sets the D/A latch to the input code that gives bipolar zero on the D/A output (Active low)10D1 (D9)DWRWrite control line (Active low)11D0 (D8)/SID \overline{A}_1 Enable for D/A converter latch (Active low)11D0 (D8)/SIDD15 (MSB)Data bit 15 (Most Significant Bit)13 R_{r2} R_{r2} D14Data bit 12DDDDD15MBBData bit 1315ACOMAD12Data bit 1117BPOBitD14Data bit 1315ACOMAD12Data bit 1018GAGD13Data bit 1018GAGD14Data bit 1117BPOBitD10Data bit 320-V_{CC}PD11Data bit 1018GAGD2Data bit 620-V_{CC}PD3Data bit 622WRVD4Data bit 5Data bit 42	Latch enable for "high byte" input (Active low). When both A_0 and A_1 are logic "0", the serial input mode is selected and the serial input is enabled.
DAC707. Offset adjust circuit is connected to the summing junction of the output amplifier. Refer to Block Diagram.erGAGain adjust pin. Refer to Connection Diagram for gain adjust circuit.6D5 (D13)Di+V _{CC} Positive supply voltage (+15V)7D4 (D12)Di-V _{CC} Negative supply voltage (-15V)7D4 (D12)Di-V _{CC} Negative supply voltage (-15V)8D3 (D11)DiCLRClear line. Sets the input latch to zero and sets the D/A latch to the input code that gives bipolar zero on the D/A output (Active low)10D1 (D9)Di $\overline{A_1}$ Enable for input latch (Active low)10D1 (D9)DiSet $\overline{A_0}$ Enable for input latch (Active low)12DCOMSetD15 (MSB)Data bit 15 (Most Significant Bit)13R _{F2} F6 ar ar ar arSetD14Data bit 13D1414V _{OUT} N _{CT} R _{F1} (DAC708)Vie St (DAC708)SetD13Data bit 11D1D1SetACOMAt St (DAC708)SetD14Data bit 1018GAGD15MSBData bit 1018GAGD16Data bit 1019+V _{CC} P1D17Data bit 1019+V _{CC} P1D18Data bit 320-V _{CC} P1D19Data bit 621-V _{CC} P1D10Data bit 721CLRCIRD6Data bit 5 <td>Input for data bit 7 if enabling low byte (LB) latch or data bit 15 if enabling the high byte (HB) latch.</td>	Input for data bit 7 if enabling low byte (LB) latch or data bit 15 if enabling the high byte (HB) latch.
adjust circuit.CCCCC+V_{CC}Positive supply voltage (+15V)7D4 (D12)D2-V_{CC}Negative supply voltage (-15V)8D3 (D11)D2CLRClear line. Sets the input latch to zero and sets the D/A latch to the input code that gives bipolar zero on the D/A output (Active low)10D1 (D9)WRWrite control line (Active low)10D1 (D9)D2 \overline{A}_1 Enable for D/A converter latch (Active low)11D0 (D8)/SID5 \overline{A}_0 Enable for input latch (Active low)12DCOMD1D15 (MSB)Data bit 15 (Most Significant Bit)13R _{F2} F6D14Data bit 1414V _{OUT} R _{F1} (DAC708)WD12Data bit 1216SJ (DAC709) Iour (DAC708)D1D14Data bit 1117BPOBit Bit BitD14Data bit 1117BPOBit Bit BitD15MSBData bit 1018GAGD16Data bit 1018GAGGD7Data bit 721CLRCLCLD6Data bit 622WRWKD6Data bit 5Data bit 5CLKKD3Data bit 325No pinKD6Data bit 325No pinKD6Data bit 326No pinK	Input for data bit 6 if enabling LB latch or data bit 14 if enabling the HB latch.
$-V_{CC}$ CLRNegative supply voltage (-15V)8 clear line. Sets the input latch to zero and sets the D/A latch to the input code that gives bipolar zero on the D/A output (Active low)9 clear line. Sets the input latch to zero and sets the D/A latch to the input code that gives bipolar zero on the D/A output (Active low)9 clear line. Sets the input latch to zero and sets the D/A latch to the input code that gives bipolar zero on the D/A output (Active low)9 clear line. Sets the input latch (Active low)10D 1 (D9)D0 D \overline{A}_{1} Enable for D/A converter latch (Active low)11D0 (D8)/SID SetD15 (MSB)Data bit 15 (Most Significant Bit)13R _{F2} Fa registrationD14Data bit 1414 V_{OUT} R _{F1} (DAC708)Via R R registrationVia R R registrationD13Data bit 13Data bit 1216SJ (DAC709) R R registrationSi (DAC709) R	Data bit 5 (LB) or data bit 13 (HB)
$\overline{\text{CLR}}$ Clear line. Sets the input latch to zero and sets the D/A D/A output (Active low)9D2 (D10)D2 $\overline{\text{WR}}$ Write control line (Active low)10D1 (D9)D1D1 $\overline{\text{A}}_1$ Enable for D/A converter latch (Active low)11D0 (D8)/SID5 $\overline{\text{A}}_0$ Enable for input latch (Active low)12DCOMD1D15 (MSB)Data bit 15 (Most Significant Bit)13R _{F2} FragretD14Data bit 14Vourt RF1 (DAC708)Vourt RF1Vourt RF1 (DAC708)Vourt RF1D13Data bit 1216SJ (DAC709) RO10SI D10 (DAC708)SI D10D14Data bit 1117BPOBi Bi D10SI RO10SI RAC708)SI RAC708)D13Data bit 1117BPOBi Bi D10SI RAC708)SI RAC708)SI RAC708)D14Data bit 1117BPOBi Bi D10SI RAC708)SI RAC708)SI RAC708)D14Data bit 1117BPOBi Bi D10SI RAC708)SI RAC708)SI RAC708)SI RAC708)D15Data bit 320-V_CcRA RAC708)SI RAC708)SI RAC708)SI RAC708)SI RAC708)SI RAC708)D14Data bit 622WRSI RAC708)SI RAC708)SI RAC708)SI RAC708)SI RAC708)SI RAC708)SI RAC708)SI RAC708)SI RAC708)SI RAC708) </td <td>Data bit 4 (LB) or data bit 12 (HB)</td>	Data bit 4 (LB) or data bit 12 (HB)
Iatch to the input code that gives bipolar zero on the D/A output (Active Iow)I0D1 (D9)D2 \overline{MR} Write control line (Active Iow)10D1 (D9)D2 \overline{A}_1 Enable for D/A converter latch (Active Iow)11D0 (D8)/SID2 \overline{A}_0 Enable for input latch (Active Iow)12DCOMD1D15 (MSB)Data bit 15 (Most Significant Bit)13 R_{F2} F_{e1} D14Data bit 1414 V_{OUT} $R_{F1} (DAC708)R_{F2}R_{F1}D13Data bit 1215ACOMAdD12Data bit 1216SJ (DAC709)I_{OUT} (DAC708)SJD11Data bit 1117BPOBibijD10Data bit 1018GAGD9Data bit 320-V_{CC}PiCOD7Data bit 321CIRCICIRD6Data bit 523\overline{CS}CICIRD6Data bit 523\overline{CS}CICIRD3Data bit 325No pinTD2Data bit 325No pinT$	Data bit 3 (LB) or data bit 11 (HB)
\overline{A}_1 Enable for D/A converter latch (Active low)11D0 (D8)/SID0 \overline{A}_0 Enable for input latch (Active low)12DCOMD1D15 (MSB)Data bit 15 (Most Significant Bit)13 R_{F2} F_{ar} D14Data bit 1414 V_{OUT} $R_{F1} (DAC708)VoutR_{F1} (DAC708)VoutR_{F1} (DAC708)D13Data bit 1315ACOMArD12Data bit 1216SJ (DAC709)Iour (DAC708)D1D11Data bit 1117BPOBitD10Data bit 1018GAGD9Data bit 721\overline{CLR}CID7Data bit 523\overline{CS}CID6Data bit 523\overline{CS}CID6Data bit 523\overline{CS}CID3Data bit 325No pinTD2Data bit 325No pinT$	Data bit 2 (LB) or data bit 10 (HB)
\overline{A}_0 Enable for input latch (Active low) 12 DCOM Dist D15 (MSB) Data bit 15 (Most Significant Bit) 13 R_{F2} Fa D14 Data bit 14 14 V_{OUT} R_{F1} (DAC708) V_{R1} D13 Data bit 13 15 ACOM Ar D12 Data bit 12 16 SJ (DAC709) SL D11 Data bit 11 17 BPO Bit D11 Data bit 11 17 BPO Bit D10 Data bit 19 19 $+V_{CC}$ Proce D8 Data bit 3 20 $-V_{CC}$ Proce Proce D7 Data bit 6 20 $-V_{CC}$ Proce Proce Proce D6 Data bit 7 21 \overline{CLR} \overline{CLR} \overline{CLR} \overline{CLR} \overline{CLR} \overline{CLR} \overline{CLR} D10 Data bit 6 22 \overline{VR} 23 \overline{CLR}	Data bit 1 (LB) or data bit 9 (HB)
D15 (MSB) Data bit 15 (Most Significant Bit) 13 R _{F2} Fairs D14 Data bit 14 14 Vout R _{F1} (DAC708) Vout D13 Data bit 13 15 ACOM A D14 Data bit 13 15 ACOM A D12 Data bit 12 16 SJ (DAC709) Su (DAC709)	Data bit 0 (LB) or data bit 8 (HB). Serial input when serial mode is selected.
D14 Data bit 14 14 V_{OUT} R_{F1} (DAC708) V_{US} R_{R1} D13 Data bit 13 15 ACOM Ar D12 Data bit 12 16 SJ (DAC709) I_{OUT} (DAC708) SI D11 Data bit 12 16 SJ (DAC709) I_{OUT} (DAC708) SI D11 Data bit 11 17 BPO Bit D10 Data bit 9 19 $+V_{CC}$ Po D8 Data bit 7 21 CLR CI D7 Data bit 5 23 CS CI D6 Data bit 5 23 CS CI D6 Data bit 3 25 No pin To D6 Data bit 3 25 No pin To D6 Data bit 3 25 No pin To D4 Data bit 3 25 No pin CI D7 Data bit 3 25 No pin CI D6 Data bit 3 25 No pin CI D7 Data bit 3 25 No pin CI <td>Digital common</td>	Digital common
D13 Data bit 13 15 ACOM Ar D12 Data bit 12 16 SJ (DAC709) Su D11 Data bit 11 17 BPO Bit D10 Data bit 10 18 GA Ga D10 Data bit 9 19 $+V_{CC}$ Pe D8 Data bit 7 20 $-V_{CC}$ Nu D7 Data bit 7 21 CLR CL D6 Data bit 6 22 WR W D5 Data bit 5 CL CL CL D4 Data bit 3 24 V_{DD} L D7 Data bit 6 22 WR W D5 Data bit 6 23 CS CL D4 Data bit 3 25 No pin L D3 Data bit 3 25 No pin CL D3 Data bit 2 26 No pin CL	Feedback resistor for internal or external operational amplifier. Connect to pin 14 when a 10V output range is desired. Leave open for a 20V output range.
D12Data bit 1216SJ (DAC709) IouT (DAC708)Su AD11Data bit 1117BPOBiD10Data bit 1018GAGD9Data bit 919+V _{CC} PdD8Data bit 820-V _{CC} PdD7Data bit 7Data bit 7CIRCIRD6Data bit 523CSCID4Data bit 523CSCID4Data bit 324V _{DD} LID3Data bit 325No pinTD2Data bit 2CICICI	Voltage output for DAC709 or feedback resistor for use with an external output op amp for the DAC708. Refer to Connection Diagram for connection of external op amp to DAC708.
D11Data bit 1117BPOBit bitD10Data bit 1018GAGD9Data bit 919+V _{CC} PoD8Data bit 820-V _{CC} NoD7Data bit 721CLRCLD6Data bit 622WRWD5Data bit 523CSCLD4Data bit 324V _{DD} LCD3Data bit 325No pinT	Analog common
D10Data bit 1018GAGiD9Data bit 919+V _{CC} PdD8Data bit 820-V _{CC} NdD7Data bit 721CLRCLD6Data bit 622WRWD5Data bit 523CSCLD4Data bit 324V _{DD} LCD3Data bit 325No pinTD2Data bit 2VPdCL	Summing junction of the internal output op amp for the DAC709, or the current output for the DAC708. Refer to Connection Diagram for connection of external op amp to DAC708.
D9Data bit 919+V _{CC} PdD8Data bit 820-V _{CC} NuD7Data bit 721CLRCLD6Data bit 622WRWD5Data bit 523CSCLD4Data bit 324V _{DD} LCD3Data bit 20ata bit 3CFNo pinD2Data bit 2CCC	Bipolar offset. Connect to pin 16 when operating in the bipolar mode. Leave open for unipolar mode.
D8Data bit 820-V_{CC}NuD7Data bit 72121-V_{CC}NuD6Data bit 622WRWD5Data bit 523CSCID4Data bit 424V_{DD}LCD3Data bit 325No pinTD2Data bit 2CCC	Gain adjust pin
D7Data bit 721CLRCLD6Data bit 622WRWD5Data bit 523CSCLD4Data bit 424VDDLCD3Data bit 325No pinTD2Data bit 2CNo pinT	Positive supply voltage (+15V)
D6Data bit 622WRWD5Data bit 523CSCID4Data bit 424V _{DD} LoD3Data bit 325No pin1D2Data bit 2(T1	Negative supply voltage (-15V)
D5Data bit 523CSCID4Data bit 424VVLoD3Data bit 325No pinLoD2Data bit 20No pinCI	Clear line. Sets the high and low byte input registers to zero and, for bipolar operation, sets the D/A register to the input code that gives bipolar zero on the D/A output. (In the unipolar mode, invert the MSB prior to the D/A.)
D4Data bit 424VDDLaD3Data bit 325No pin1D2Data bit 226No pin1	Write control line
D3Data bit 325No pinD2Data bit 226No pin(T	Chip select control line
D2 Data bit 2 26 No pin (T	Logic supply (+5V)
D1 Data bit 1 27 No pin	(The DAC708 and DAC709 are in 24-pin packages)
D0 (LSB) Data bit 0 (Least Significant Bit) 28 No pin	



DISCUSSION OF SPECIFICATIONS

DIGITAL INPUT CODES

For bipolar operation, the DAC707/708/709 accept positivetrue binary two's complement input code. For unipolar operation (DAC708/709 only) the input code is positive-true straight-binary provided that the MSB input is inverted with an external inverter. See Table I.

	ANALOG OUTPUT								
Digital	Unipolar Straight Binary ⁽¹⁾	Binary Two's Complement							
Input	(DAC708/709 only; connected	(Bipolar operation;							
Codes	for Unipolar operation)	all models)							
7FFF _H	+1/2 Full Scale –1LSB ⁽²⁾	+Full Scale							
0000 _H	Zero	Zero							
FFFF _H	+Full Scale	–1LSB							
8000 _H	+1/2 Full Scale	–Full Scale							
NOTES: (1) MSB must be inverted externally. (2) Assumes MSB is inverted externally.									

TABLE I. Digital Input Codes.

ACCURACY

Linearity

This specification describes one of the most important measures of performance of a D/A converter. Linearity error is the deviation of the analog output from a straight line drawn through the end points (–Full Scale point and +Full Scale point).

Differential Linearity Error

Differential Linearity Error (DLE) of a D/A converter is the deviation from an ideal 1LSB change in the output when the input changes from one adjacent code to the next. A differential linearity error specification of $\pm 1/2$ LSB means that the output step size can be between 1/2LSB and 3/2LSB when the input changes between adjacent codes. A negative DLE specification of -1LSB maximum (-0.006% for 14-bit resolution) insures monotonicity.

Monotonicity

Monotonicity assures that the analog output will increase or remain the same for increasing input digital codes. The DAC707/708/709 are specified to be monotonic to 14 bits over the entire specification temperature range.

DRIFT

Gain Drift

Gain Drift is a measure of the change in the full-scale range output over temperature expressed in parts per million per degree centigrade (ppm/°C). Gain drift is established by: (1) testing the end point differences at t_{MIN} , +25°C and t_{MAX} ; (2) calculating the gain error with respect to the +25°C value; and (3) dividing by the temperature change.

Zero Drift

Zero Drift is a measure of the change in the output with $0000_{\rm H}$ applied to the D/A converter inputs over the specified temperature range. (For the DAC708/709 in unipolar mode,

the MSB must be inverted). This code corresponds to zero volts (DAC707 and DAC709) or zero milliamps (DAC708) at the analog output. The maximum change in offset at t_{MIN} or t_{MAX} is referenced to the zero error at +25°C and is divided by the temperature change. This drift is expressed in FSR/°C.

SETTLING TIME

Settling time of the D/A is the total time required for the analog output to settle within an error band around its final value after a change in digital input. Refer to Figure 1 for typical values for this family of products.

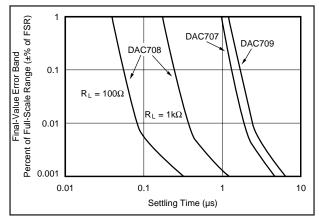


FIGURE 1. Final-Value Error Band Versus Full-Scale Range Settling Time.

Voltage Output

Settling times are specified to $\pm 0.003\%$ of FSR ($\pm 1/2$ LSB for 14 bits) for two input conditions: a full-scale range change of 20V ($\pm 10V$) or 10V ($\pm 5V$ or 0 to 10V) and a 1LSB change at the "major carry", the point at which the worst-case settling time occurs. (This is the worst-case point since all of the input bits change when going from one code to the next.)

Current Output

Settling times are specified to $\pm 0.003\%$ of FSR for a fullscale range change for two output load conditions: one for 10Ω to 100Ω and one for 1000Ω . It is specified this way because the output RC time constant becomes the dominant factor in determining settling time for large resistive loads.

COMPLIANCE VOLTAGE

Compliance voltage applies only to current output models. It is the maximum voltage swing allowed on the output current pin while still being able to maintain specified accuracy.

POWER SUPPLY SENSITIVITY

Power supply sensitivity is a measure of the effect of a change in a power supply voltage on the D/A converter



output. It is defined as a percent of FSR change in the output per percent of change in either the positive supply $(+V_{CC})$, negative supply $(-V_{CC})$ or logic supply (V_{DD}) about the nominal power supply voltages (see Figure 2). It is specified for DC or low frequency changes. The typical performance curve in Figure 2 shows the effect of high frequency changes in power supply voltages.

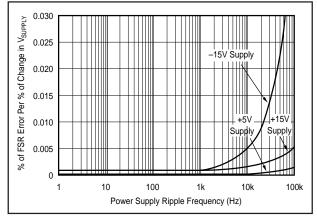


FIGURE 2. Power Supply Rejection Versus Power Supply Ripple Frequency.

OPERATING INSTRUCTIONS

POWER SUPPLY CONNECTIONS

For optimum performance and noise rejection, power supply decoupling capacitors should be added as shown in the Connection Diagram. 1 μ F tantalum capacitors should be located close to the D/A converter.

EXTERNAL ZERO AND GAIN ADJUSTMENT

Zero and gain may be trimmed by installing external zero and gain potentiometers. Connect these potentiometers as shown in the Connection Diagram and adjust as described below. TCR of the potentiometers should be 100ppm/°C or less. The 3.9M Ω and 270k Ω resistors (±20% carbon or better) should be located close to the D/A converter to prevent noise pickup. If it is not convenient to use these high-value resistors, an equivalent "T" network, as shown in Figure 3, may be substituted in place of the 3.9M Ω resistor. A 0.001µF to 0.01µF ceramic capacitor should be connected from GAIN ADJUST to ANALOG COMMON to prevent noise pickup. Refer to Figures 4 and 5 for the relationship of zero and gain adjustments to unipolar D/A converters.

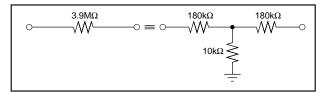


FIGURE 3. Equivalent Resistances.

Zero Adjustment

For unipolar (USB) configurations, apply the digital input code that produces zero voltage or zero current output and adjust the zero potentiometer for zero output.

For bipolar (BTC) configurations, apply the digital input code that produces zero output voltage or current. See Table II for corresponding codes and connection diagrams for zero adjustments circuit connections. Zero calibration should be made before gain calibration.

Gain Adjustment

Apply the digital input that gives the maximum positive output voltage. Adjust the gain potentiometer for this positive full-scale voltage. See Table II for positive full-scale voltages and the Connection Diagrams for gain adjustment circuit connections.

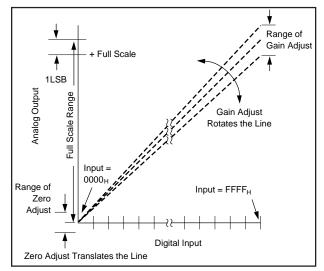


FIGURE 4. Relationship of Zero and Gain Adjustments for Unipolar D/A Converters, DAC708 and DAC709.

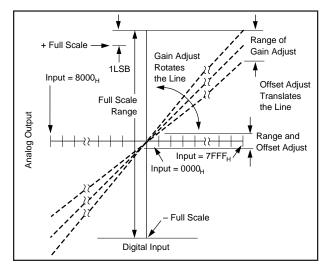


FIGURE 5. Relationship of Zero and Gain Adjustments for Bipolar D/A Converters, DAC707 and DAC708/ 709



						VOLTA	GE OUTPL	JT MODELS					
Digital Analog Output				Digital			А	nalog Outpu	ut				
Input		Unipolar, 0 to +10V ⁽¹⁾				Input		Bipolar, ±10	V		Bipolar, ±5\	/	
Code		Bit	15-Bit	14-Bit	Units	Code	16-Bit	15-Bit	14-Bit	16-Bit	15-Bit	14-Bit	Units
One LSB FFFF _H 0000 _H	15 +9.99	9985	305 +9.99969 0	610 +9.99939 0	μV V V	One LSB 7FFFH 8000H	305 +9.99960 -10.0000		1224 +9.99878 -10.0000	153 +4.99980 -5.0000	305 +4.99970 -5.0000	610 +4.99939 -5.0000	μV V V
CURRENT OUTPUT MODELS													
Digital		Analog Output						Digital		Analog C	Dutput		
Input			Unipolar	, 0 to –2mA ^{(*}	1)			Input		Bipolar, ±1mA			
Code		16	-Bit 1	5-Bit	14-Bit	Unit	s	Code	16-Bit	15-B	it 1	4-Bit	Units
One LSB FFFF _H 0000 _H		-1.9).061 .99994 0	0.122 -1.99988 0	μA mA mA	7	ne LSB FFF _H 000 _H	0.031 -0.99997 +1.00000		994 –0.	.122 99988 00000	μA mA mA
NOTE: (1)	NOTE: (1) MSB assumed to be inverted externally.												

TABLE II. Digital Input and Analog Output Voltage/Current Relationships.

INTERFACE LOGIC AND TIMING

DAC708/709

The signals CHIP SELECT (\overline{CS}), WRITE (\overline{WR}), register enables (\overline{A}_0 , \overline{A}_1 , and \overline{A}_2) and CLEAR (\overline{CLR}), provide the control functions for the microprocessor interface. They are all active in the "low" or logic "0" state. \overline{CS} must be low to access any of the registers. \overline{A}_0 and \overline{A}_1 steer the input 8-bit data byte to the low- or high-byte input latch respectively. \overline{A}_2 gates the contents of the two input latches through to the D/A latch in parallel. The contents are then applied to the input of the D/A converter. When WR goes low, data is strobed into the latch or latches which have been enabled.

The serial input mode is activated when both \overline{A}_0 and \overline{A}_1 are logic "0" simultaneously. The D0 (D8)/SI input data line accepts the serial data MSB first. Each bit is clocked in by a WR pulse. Data is strobed through to the D/A latch by \overline{A}_2 going to logic "0" the same as in the parallel input mode.

Each of the latches can be made "transparent" by maintaining its enable signal at logic "0". However, as stated above, when both \overline{A}_0 and \overline{A}_1 are logic "0" at the same time, the serial mode is selected.

The CLR line resets both input latches to all zeros and sets the D/A latch to 0000_{H} . This is the binary code that gives a null, or zero, at the output of the D/A in the bipolar mode. In the unipolar mode, activating CLR will cause the output to go to one-half of full scale.

The maximum clock rate of the latches is 10MHz. The minimum time between write (WR) pulses for successive enables is 20ns. In the serial input mode (DAC708 and DAC709), the maximum rate at which data can be clocked into the input shift register is 10MHz.

The timing of the control signals is given in Figure 6.

DAC707

The DAC707 interface timing is the same as that described above except instead of two 8-bit separately-enabled input latches, it has a single 16-bit input latch enabled by \overline{A}_0 . The

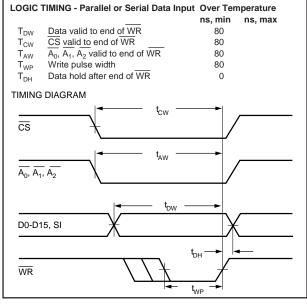


FIGURE 6. Logic Timing Diagram.

D/A latch is enabled by \overline{A}_1 . Also, there is no serial-input mode and no $\overline{\text{CHIP SELECT}}$ ($\overline{\text{CS}}$) line.

INSTALLATION CONSIDERATIONS

Due to the extremely-high accuracy of the D/A converter, system design problems such as grounding and contact resistance become very important. For a 16-bit converter with a +10V full-scale range, 1LSB is 153μ V. With a load current of 5mA, series wiring and connector resistance of only $30m\Omega$ will cause the output to be in error by 1LSB. To understand what this means in terms of a system layout, the resistance of typical 1 ounce copper-clad printed circuit board material is approximately $1/2m\Omega$ per square. In the example above, a 10 milliinch-wide conductor 60 milliinches long would cause a 1LSB error.



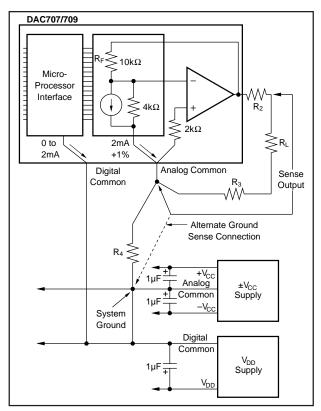


FIGURE 7. DAC707/709 Bipolar Output Circuit (Voltage Out).

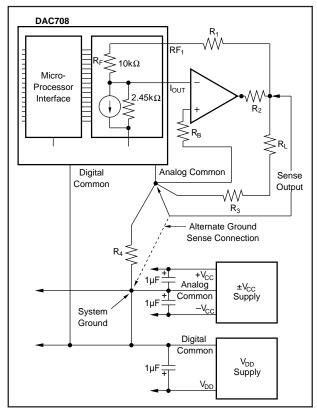


FIGURE 8. DAC708 Bipolar Output Circuit (with External Op Amp).

In Figures 7 and 8, lead and contact resistances are represented by R_1 through R_5 . As long as the load resistance R_L is constant, R_2 simply introduces a gain error and can be removed with gain calibration. R_3 is part of R_L if the output voltage is sensed at ANALOG COMMON.

Figures 8 and 9 show two methods of connecting the current output model with an external precision output op amp. By sensing the output voltage at the load resistor (connecting R_F to the output of the amplifier at R_L) the effect of R_1 and R_2 is greatly reduced. R_1 will cause a gain error but is independent of the value of R_L and can be eliminated by initial calibration adjustments. The effect of R_2 is negligible because it is inside the feedback loop of the output op amp and is therefore greatly reduced by the loop gain.

In many applications it is impractical to sense the output voltage at ANALOG COMMON. Sensing the output voltage at the system ground point is permissible because these converters have separate analog and digital common lines and the analog return current is a near-constant 2mA and varies by only 10µA to 20µA over the entire input code range. R_4 can be as large as 3 Ω without adversely affecting the linearity of the D/A converter. The voltage drop across R_4 is constant and appears as a zero error that can be nulled with the zero calibration adjustment.

Another approach senses the output at the load as shown in Figure 9. In this circuit the output voltage is sensed at the load common and not at the D/A converter common as in the previous circuits. The value of R_6 and R_7 must be adjusted for maximum common-mode rejection across R_L . The effect of R_4 is negligible as explained previously.

The D/A converter and the wiring to its connectors should be located to provide optimum isolation from sources of RFI and EMI. The key to elimination of RF radiation or pickup is small loop area. Signal leads and their return conductors should be kept close together such that they present a small flux-capture cross section for any external field.

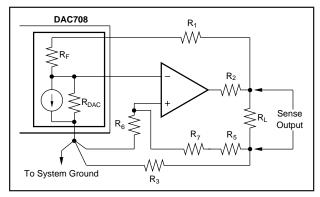


FIGURE 9. Alternate Connection for Ground Sensing at the Load (Current Output Models).



BURN-IN SCREENING

Burn-in screening is an option available for the DAC707. Burn-in duration is 160 hours at the temperature shown below (or equivalent combination of time and temperature).

Product	Temp. Range	Burn-In Screening
DAC707JP-BI	0°C to 70°C	100°C
DAC707KP-BI	0°C to 70°C	100°C
DAC707KH-BI	$-25^{\circ}C$ to $+85^{\circ}C$	125°C
DAC707BH-BI	$-25^{\circ}C$ to $+85^{\circ}C$	125°C
DAC707SH-BI	$-55^{\circ}C$ to $+125^{\circ}C$	125°C

All units are tested after burn-in to ensure that grade specifications are met.

APPLICATIONS

LOADING THE DAC709 SERIALLY ACROSS AN ISOLATION BARRIER

A very useful application of the DAC709 is in achieving low-cost isolation that preserves high accuracy. Using the serial input feature of the input register pair, only three signal lines need to be isolated. The data is applied to pin 11 in a serial bit stream, MSB first. The WR input is used as a data strobe, clocking in each data bit. A RESET signal is provided for system startup and reset. These three signals are each optically isolated. Once the 16 bits of serial data have been strobed into the input register pair, the data is strobed through to the D/A register by the "carry" signal out of a 4-bit binary synchronous counter that has counted the $16 \overline{\text{WR}}$ pulses used to clock in the data. The circuit diagram is given in Figure 10.

CONNECTING MULTIPLE DAC707s TO A 16-BIT MICROPROCESSOR BUS

Figure 11 illustrates the method of connecting multiple DAC707s to a 16-bit microprocessor bus. The circuit shown has two DAC707s and uses only one address line to select either the input register or the D/A register. An external address decoder selects the desired converter.



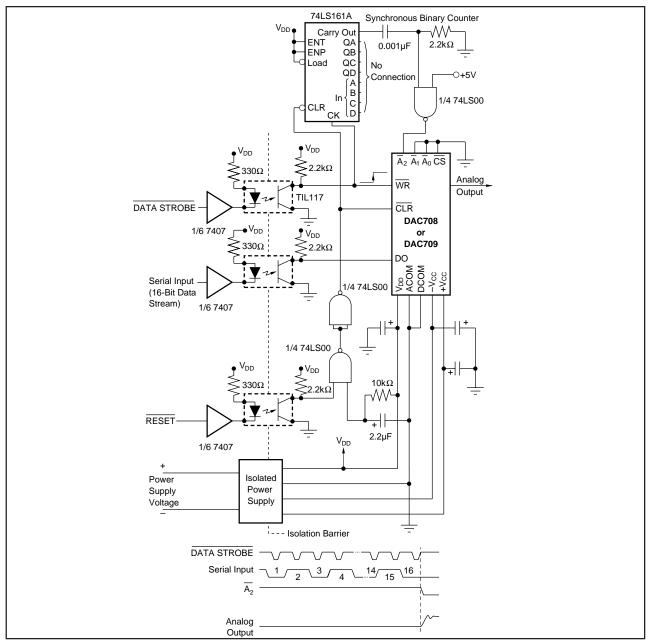


FIGURE 10. Serial Loading of Electrically Isolated DAC708/709.

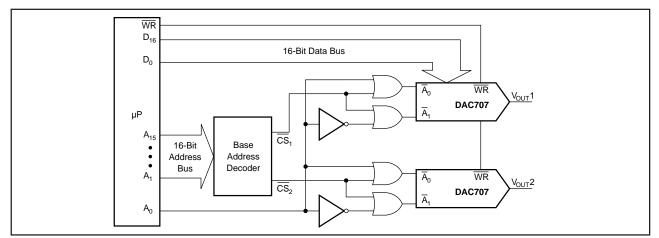


FIGURE 11. Connecting Multiple DAC707s to a 16-Bit Microprocessor.

DAC707/708/709



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
DAC707JP	NRND	PDIP	NTD	28	13	TBD	CU SNPB	N / A for Pkg Type
DAC707JP-BI	OBSOLETE	PDIP	NTD	28		TBD	Call TI	Call TI
DAC707KP	NRND	PDIP	NTD	28	13	TBD	CU SNPB	N / A for Pkg Type
DAC707KP-5	OBSOLETE	PDIP	NTD	28		TBD	Call TI	Call TI
DAC707KP-7	OBSOLETE	PDIP	NTD	28		TBD	Call TI	Call TI
DAC707KP-BI	OBSOLETE	PDIP	NTD	28		TBD	Call TI	Call TI
DAC709KH	OBSOLETE	CDIP SB	JDM	24		TBD	Call TI	Call TI
DAC709KH-2	OBSOLETE	CDIP SB	JDM	24		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

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